



Electronic Packaging: Design, Materials, Process, and Reliability

John H. Lau, C.P. Wong, J.L. Prince

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The ultimate, up-to-the-minute electronic packaging resource

The ever-increasing pin counts and clock speeds of modern electronics continue to "push the performance envelope" with regard to designing packaging and interconnection solutions that can meet increasingly challenging requirements. Here's the help you need!

For the first time, four well-known experts representing the four relevant fields--mechanical engineering, electrical engineering, thermal management, and materials--team up to provide a single-volume comprehensive reference that explains packaging and interconnection basics, details design tradeoff considerations, and presents specific system-level solutions. This unprecedented and unsurpassed multi-disciplinary coverage not only includes all the new technologies--BGA, Flip Chip, DCA, and CSP--it shows how they can be most effectively integrated.

With its clear explication of both theoretical and practical issues, *Electronic Packaging* will be of considerable and continuing value if you hope to design and/or refine more reliable, robust, and cost-effective packaging solutions for virtually any interconnect system.

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